first casing half 95 by means of mounting members 151a, 151b, and 151c, and a first control board 135 mounted on the first casing half 95 with a gap between the second control board 136 and the first control board 135. The first control board 135 is overlapped with a portion of the second control board 136. The gap between the first and second control boards 135 and 136 is established by collars 142 and 143 in which bolts are inserted.

Please **rewrite the paragraph beginning on page 15, line 21**, and **ending on page 16, line 5**, as follows:

The second control board 136, which is preferably configured as a printed wiring board, has an area extending from the inner peripheral wall of the first casing half 95 to the periphery of the first bearing portion 107. In other words, the second control board 136 has an area extending to a position at which it is overlapped with the motor 21, as seen from the axial direction A of the drive motor 21. Control devices such as a CPU 20, a capacitor 29, and relay 30 are mounted on the second control board 136. In order to effectively use a space on the second control board 136, the CPU having a low height and a large area is disposed in the gap between a portion, overlapped with the drive motor 21, of the second control board 136 and the drive motor 21.

Please **rewrite the paragraph beginning on page 16, line 6**, as follows:

The first control board 135, which may be configured as a light metal board having a good thermal conductivity, such as aluminum, is directly attached on the inner wall surface

of the first casing half 95. Devices such as a FET 27 and a diode 28 are mounted on the first control board 135 while being put between the second control board 136 and the first control board 135. The heat generated from these devices are transferred to the first casing half 95 via the first control board 135. Accordingly, it is possible to effectively prevent the above devices from being heated to high temperatures.

Please **rewrite the paragraph beginning on page 16, line 18**, and **ending on page 17, line 1**, as follows:

A second control board 136, such as a printed wiring board, is disposed on a plane behind the motor 21 and perpendicular to the motor shaft as seen along the direction A of Fig. 11, so as to be near the motor 21. The second control board 136 has a circular hole 310 centered at the motor shaft, and a motor shaft supporting portion 300 as a case boss portion having a circular cross-section inserted in the circular hole 310. An annular vibration-proof rubber ring 301 is mounted between the inner periphery of the circular hole and the outer periphery of the motor shaft supporting portion 300 in a state being elastically compressed therebetween.

Please **rewrite the paragraph beginning on page 17, line 2**, as follows:

As in the exemplary embodiments in Figs. 1 and 3, the capacitor 29, relay 30, and the like are mounted on the surface of a portion, not overlapped with the motor 21, of the second control board 136, and a part having a low height and a relatively large area, such as the CPU

20 (not shown), is mounted on the surface of a portion, overlapped with the motor 21, of the second control board 136. A first control board 302, which may be a light metal board having good thermal conductivity, for example, an aluminum board, is supported on the back surface of a portion of the second control board 136 so as to be overlapped thereto.

Please **rewrite the paragraph beginning on page 17, line 10**, as follows:

A central portion of the first control board 302 is mounted to the inner wall surface of the first casing half 95 (see Fig. 1) with a screw 303. An insertion hole 304 in which a tool for turning the screw 303 is to be inserted is formed in the first control board 136 at a position facing to the screw 303.

Please **rewrite the paragraph beginning on page 17, line 14**, as follows:

The devices such as the FET 27 and diode 28 are mounted on the back surface of the second control board 136 so as to be located in a space between the first control board 302 and the second control board 136. The upper surfaces of these devices are in contact with the first control board 302. Accordingly, the heat generated from the devices such as the FET 27 and the diode 28 is transferred to the first casing half 95 via the first control board 302; therefore, these devices can be effectively prevented from being heated to high temperatures.

Please **rewrite the paragraph beginning on page 17, line 21**, as follows:

Referring back to FIG. 1 and the embodiment described initially, a speed sensor 145 for sensing a magnetic body 144 provided on the driven gear 127 for detecting the rotational